# **SKKE 212/16 H2**



# SEMIPACK® 2

### **Rectifier Diode Modules**

#### **SKKE 212/16 H2**

#### Features\*

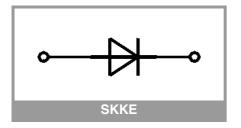
- Heat transfer through aluminum oxide ceramic insulated metal baseplate
- Hard soldered joints for high reliability
- UL recognized, file no. E63532

### **Typical Applications**

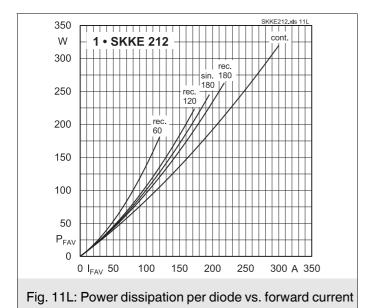
- Rectifiers
- · Free-wheeling diodes
- Reverse-polarity protection

Absolute Maximum Ratings								
Symbol	Conditions		Values	Unit				
Recitifier	Diode							
I <sub>FAV</sub>	sin. 180° T <sub>j max</sub> = 135 °C	T <sub>c</sub> = 85 °C	213	Α				
		T <sub>c</sub> = 100 °C	165	Α				
I <sub>FSM</sub>	10 ms	T <sub>j</sub> = 25 °C	6600	Α				
		T <sub>j</sub> = 135 °C	5500	Α				
i <sup>2</sup> t	10 ms	T <sub>j</sub> = 25 °C	217800	A <sup>2</sup> s				
	101115	T <sub>j</sub> = 135 °C	151250	A <sup>2</sup> s				
$V_{RSM}$	T <sub>j</sub> = 25 °C		1700 V					
$V_{RRM}$	T <sub>j</sub> = 25 °C		1600	V				
Tj			-40 135	°C				
Module								
T <sub>stg</sub>			-40 125	°C				
V <sub>isol</sub>	a.c.; 50 Hz; r.m.s.	1 min	3000	V				
	a.c., 50 mz, 1.111.5.	1 s	3600	V				

Characteristics									
Symbol	Conditions		min.	typ.	max.	Unit			
Diode			·						
$V_{F}$	$T_j = 25 ^{\circ}\text{C}, I_F = 500 \text{A}$				1.40	V			
$V_{F0}$	T <sub>j</sub> = 135 °C				0.75	V			
r <sub>F</sub>	T <sub>j</sub> = 135 °C				1.05	mΩ			
I <sub>R</sub>	$T_j = 135$ °C, $V_{RD} = V_{RRM}$				9	mA			
R <sub>th(j-c)</sub>	cont.	per chip			0.18	K/W			
		per module			0.18	K/W			
R <sub>th(j-c)</sub>	sin. 180°	per chip			0.18	K/W			
		per module			0.18	K/W			
Module									
R <sub>th(c-s)</sub>	chip			0.05		K/W			
	module			0.05		K/W			
Ms	to heatsink M5		4.25		5.75	Nm			
Mt	to terminals M6		4.25		5.75	Nm			
а					5 * 9.81	m/s²			
w				165		g			



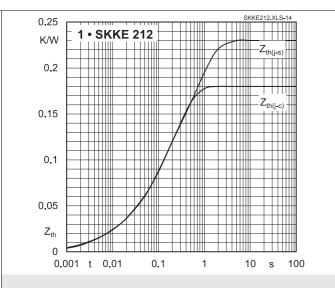
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W 0.4 300 250 200 0.8 150 100 50  $\mathsf{P}_{\mathsf{FAV}}$ 0 0  $\mathsf{T}_\mathsf{a}$ 50 °C 150 Fig. 11R: Power dissipation per diode vs. ambient

350

temperature



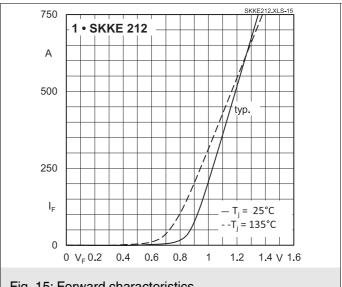
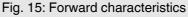
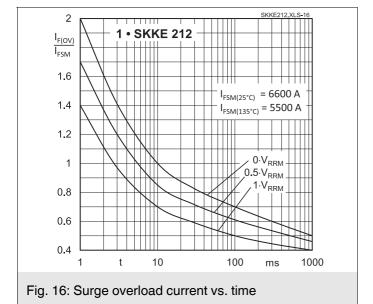
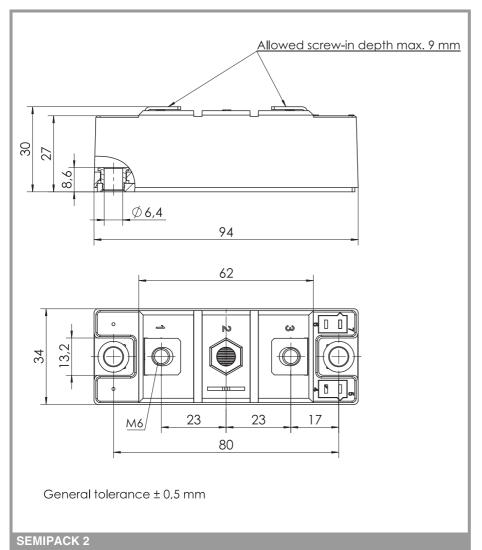


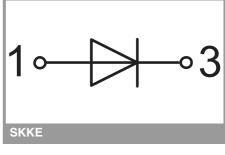
Fig. 14: Transient thermal impedance vs. time





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This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

#### \*IMPORTANT INFORMATION AND WARNINGS

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